SMD Common Mode Choke - 1210H (USB 3.0)



Features & Application

• For common mode noise suppression in high speed

differential signal lines: USB3.0, IEEE1394, LVDS,

•Up to 6.0/7.5 GHz differential mode 3 dB cutoff frequency

Core material Ferrite

Environmental RoHS compliant, halogen free

Ambient temperature -40° C to $+85^{\circ}$ C with Irms current

Maximum part temperature 105°C (ambient + temp rise)

Storage temperature Component: -40°C to +105°C.

Tape and reel packaging: -40°C to +80



Resistance to soldering heat Max three 40 second reflows at +260°C, parts cooled to room temperature between cycles Moisture Sensitivity Level (MSL) 1 (unlimited floor life at <30°C /85% relative humidity) 85% relative humidity)

★ When ordering, please check part number

Part number		DC Resistance (Ω) max	Irms (mA)
CMC1210H250-0.42AT	25	0.25	420
CMC1210H350-0.42AT	35	0.25	420
CMC1210H600-0.4AT	60	0.3	400
CMC1210H900-0.4AT	90	0.3	400

Isolation (Vrms) : 250V. Winding to winding isolation (hipot) tested for one minute.

▲ →	<mark>← B</mark> →	H	Dimensions	
Epoxy			А	1.2±0.1
	с	F	В	1.0±0.1
			С	0.8±0.1
Terminations		G	D	0.36 typ
Wires (1) ↓ (4) ↓	Foria 1 and simula	Recommended Land Patter	Е	0.33 typ
	Equivalent circuit		F	1.0 typ
	2		G	0.59 typ
	INO POIATILY		Н	0.33 typ
			Ι	0.28 typ
			unit	t : mm

Impedance/Inductance/Q/	LCR Angilent E4991A		
Resistance DC	Chroma 16502		
Current per winding that causes a 20°C rise from 25°C ambient			
Electrical specifications at 25°C			

Weight 2.8 – 5.3 mg.

Packaging 2000/7 " reel; Plastic tape: 8 mm wide.

Packaging will different, accroding the various chip size.

Contact Us		
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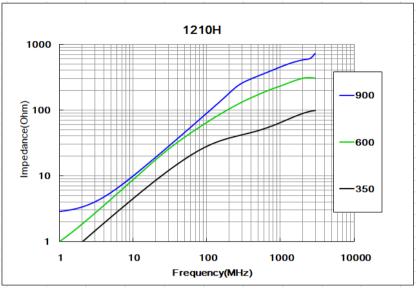
Official Website :

https://www.bing-ri.com.tw/

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Typical Impedance vs Frequency



GENERAL CHARACTERISTICS

1. Operating temperature range: $-40 \text{ TO} + 125^{\circ}$ (Includes temperature when the coil is heated)

2. External appearance: On visual inspection, the coil has no external defects.

3. Terminal strength: After soldering. Between copper plate and terminals of coil. Push in two directions of X.Ywithstanding at below conditions.

Terminal should not peel off. (refer to figure at right) 0.5kg Min -1210

4. Insulating resistance: Over 100M Ω at 100V D.C. between coil and core

5. Dielectric strength: No dielectric breakdown at 100V D.C. for 1 minute between coil and core

6. Temperature characteristics: Inductance coefficient $(0 \sim 2,000) \times 10^{-6}$ (°C -25~+80). °C,

inductance deviation within±5.0%, after 96 hours.

7. Humidity characteristics (Moisture Resistance): Inductance deviation within $\pm 5\%$, after 96 hours in 90~95% relative humidity at 40 ± 2 and 1 hour drying under normal condition.

8. Vibration resistance: Inductance deviation within $\pm 5\%$, after vibration for 1 hour. In each of three orientations at sweep vibration (10~55~10 Hz) with 1.5mm P-P amplitudes.

9. Shock resistance: Inductance deviation within $\pm 5\%$, after being dropped once with 981m/s2

(100G) shock attitude upon a rubber block method shock testing machine, in three different

10. Resistance to Soldering Heat: 260, 10 seconds(See attached recommend reflow)

11. Storage environment: Storage condition: Temperature Range: $10 \sim 35$ (Generally: $21 \sim 31$),

Humidity Range: 50% ~ 80% RH (Generally: 65% ~ 75%); Transportation condition:

Temperature Range: -35 ~ 85, Humidity Range: 50% ~ 95% RH

300

12. Use components within 12 months. If 12 months or more have elapsed, check soldarability before use. 13. Reflow profile recommend:

Lead-free heat en duran ce test

T(°C) 300 260°C 250 230°C 200 150 100 50 T(s 1 20 180 240

60

